



# SA12B5 SA16B3 / SA16B6 SCHOTTKY ARRAYS

Application Specific Discretes  
A.S.D.<sup>TM</sup>

## MAIN APPLICATIONS

Any electronic equipment where suitable bus termination is required to avoid signal reflections and distortions :

- PCs
- Workstations
- High frequency processor boards
- Dataline interface

## DESCRIPTION

Dedicated to bus termination, the Schottky arrays SA12B5, SA16B3 and SA16B6 minimise stray emissions from PCB tracks. They provide suitable termination by avoiding signal reflexions and distortions.

## FEATURES

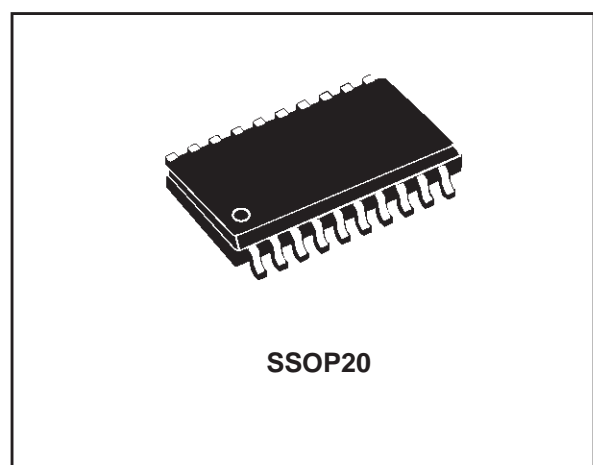
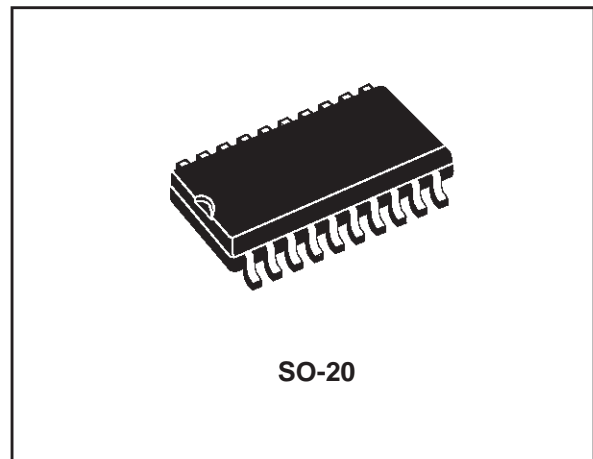
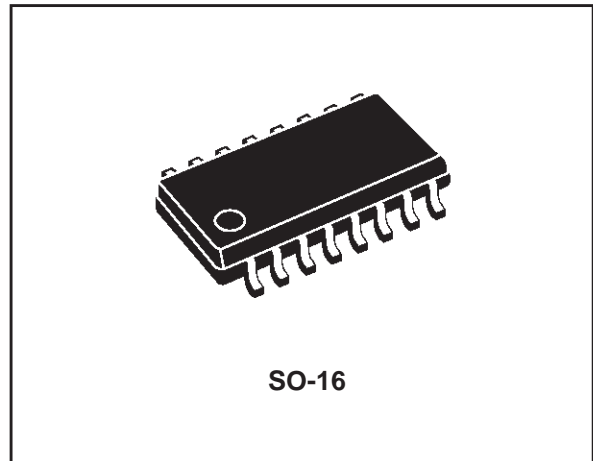
- 12-BIT (SA12) OR 16-BIT (SA16) DUAL SCHOTTKY DIODE ARRAYS
- REVERSE VOLTAGE :  $V_{RRM} = 7.5 V$
- FORWARD VOLTAGE  $V_F < 1.3 V$

## BENEFITS

- Provides impedance matching, and minimizes distortion.
- Lowers EMI / RFI radiation.
- Eliminates negative voltage : minimizes risk of latch-up for sensitive ICs.
- Saves valuable space on board.

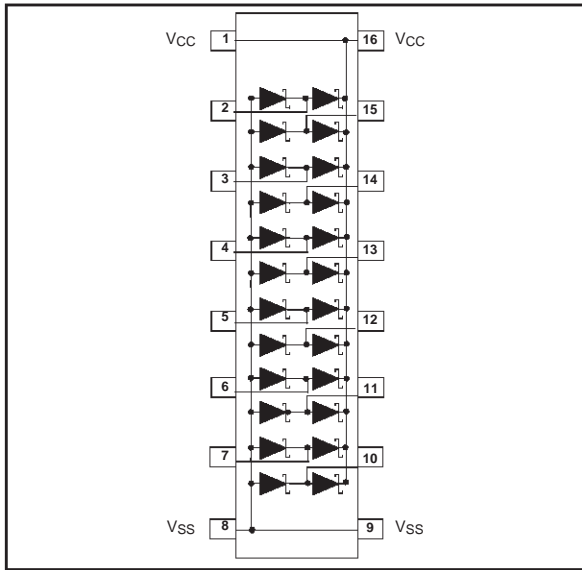
## COMPLIES WITH FOLLOWING STANDARD :

- MIL STD 883C - Method 3015-6 - class 3
- IEC1000-4-2 level 4

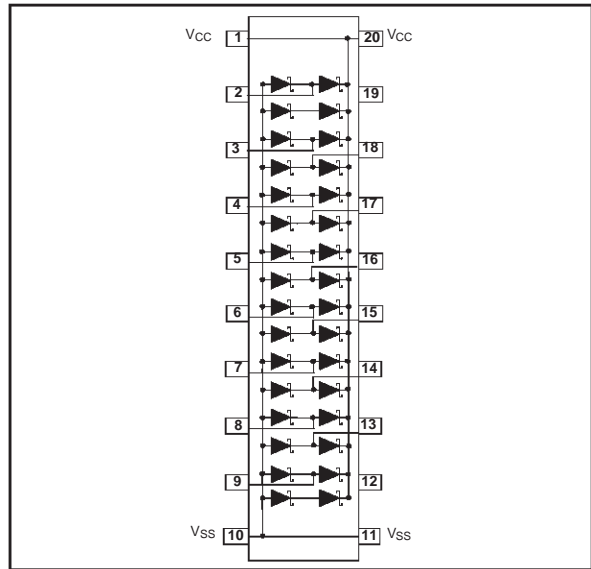


## SA12B5 / SA16B3 / SA16B6

### FUNCTIONAL DIAGRAM (SO-16)



### FUNCTIONAL DIAGRAM (SO-20 and SSOP20)



### ABSOLUTE MAXIMUM RATINGS (T<sub>amb</sub> = 25 °C)

| Symbol           | Parameter and test conditions   |                           | Value       | Unit |
|------------------|---|---------------------------|-------------|------|
| P                | Power dissipation   | SO-20<br>SO-16 and SSOP20 | 1250<br>850 | mW   |
| V <sub>OP</sub>  | Maximum operating voltage (V <sub>CC</sub> - V <sub>SS</sub> )                        |                           | 7.5         | V    |
| V <sub>PP</sub>  | Maximum electrostatic discharge<br>MIL STD 883C - Method 3015-6 / IEC1000-4-2 contact |                           | 8           | kV   |
| T <sub>OP</sub>  | Operating temperature range (see note 1)  |                           | -40 to +85  | °C   |
| T <sub>stg</sub> | Storage temperature range   |                           | -55 to +150 | °C   |
| T <sub>L</sub>   | Maximum lead temperature for soldering during 10s                                     |                           | 260         | °C   |
| T <sub>j</sub>   | Maximum junction temperature  |                           | 150         | °C   |

Note 1: within the T<sub>OP</sub> range, the SAxx keep on operating. The impacts of the ambient temperature are given by derating curves on the following page.

### ELECTRICAL CHARACTERISTICS (T<sub>amb</sub> = 25°C)

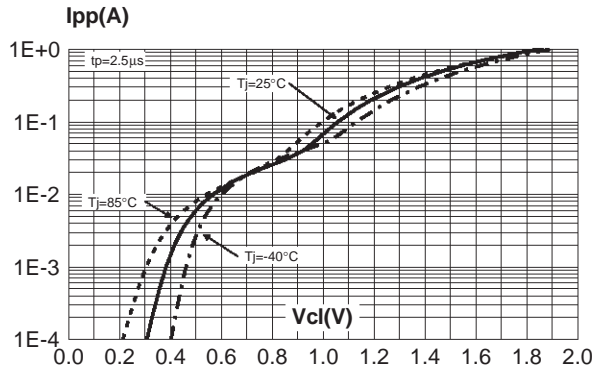
| Symbol         | Parameter and test conditions              |  | Typ. | Max.        | Unit |
|----------------|--|--|------|-------------|------|
| I <sub>R</sub> | Leakage current @ V <sub>RRM</sub> = 7.5 V |  |      | 5           | μA   |
| V <sub>F</sub> | Forward voltage<br>(see note 2)            | I <sub>PP</sub> = 18 mA<br>I <sub>PP</sub> = 50 mA |      | 1.05<br>1.3 | V    |
| C <sub>d</sub> | Capacitance                                | V <sub>bias</sub> = 0V, F = 1MHz                   |      | 16          | pF   |

Note 2: for both pull-up and pull-down schottky diodes.

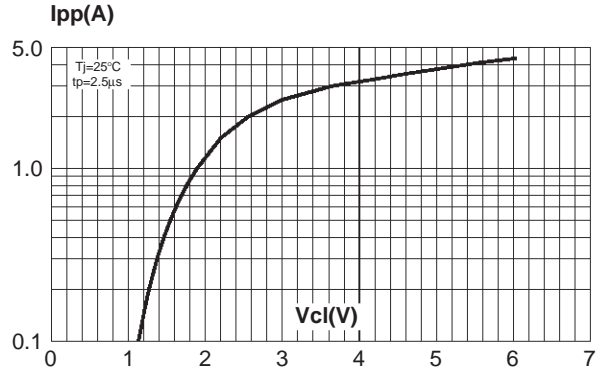
### THERMAL RESISTANCE

| Symbol               | Parameter           | Packages                  | Value      | Unit |
|----------------------|---------------------|---------------------------|------------|------|
| R <sub>th(j-a)</sub> | Junction to ambient | SO-16 and SSOP20<br>SO-20 | 140<br>100 | °C/W |

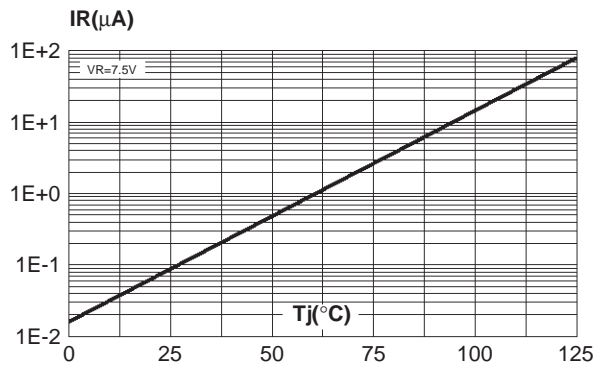
**Fig1-1:** Clamping forward voltage versus peak pulse current (typical values, low level).



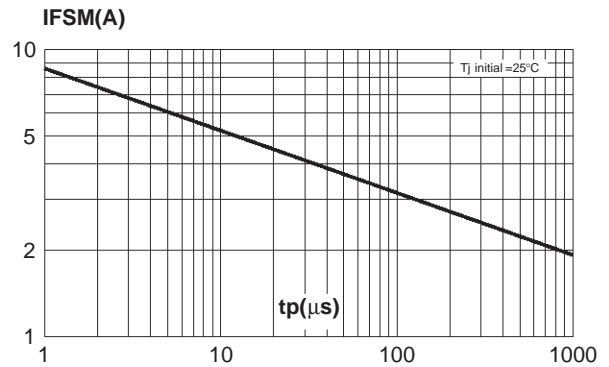
**Fig1-2:** Clamping forward voltage versus peak pulse current (typical values, high level).



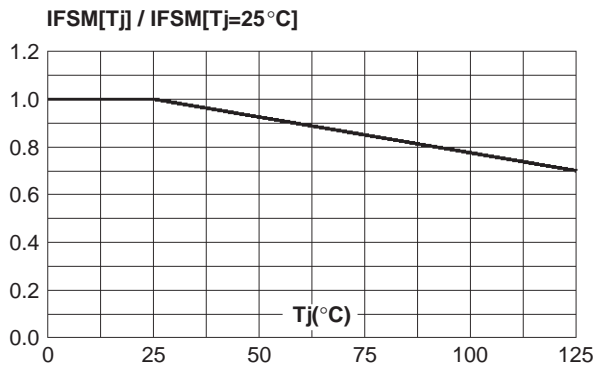
**Fig 2:** Leakage current versus junction temperature (typical values).



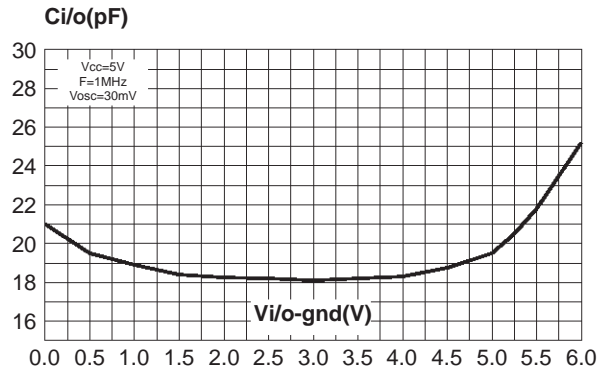
**Fig 3:** Non repetitive surge peak forward current versus pulse duration (rectangular waveform).



**Fig 4:** Non repetitive surge peak forward current versus initial junction temperature.

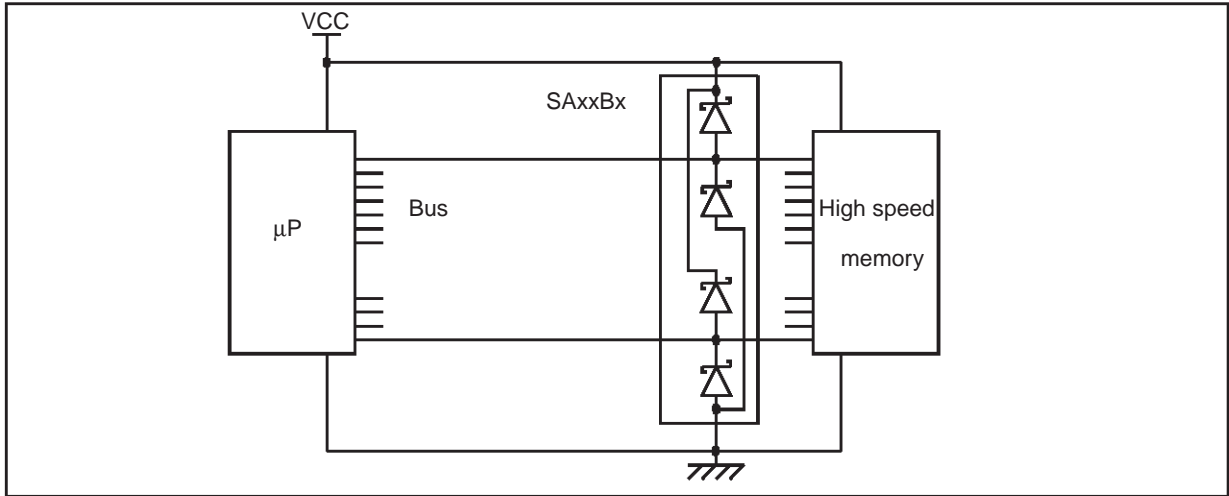


**Fig 5:** Capacitance between input or output and ground versus applied voltage (typical values).



# SA12B5 / SA16B3 / SA16B6

## TYPICAL APPLICATION



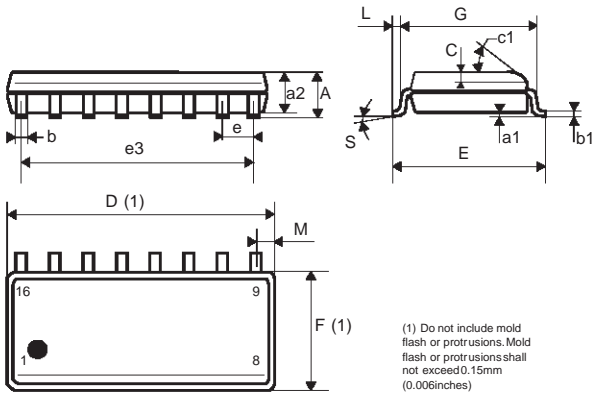
## MARKING

| Type   | Package | Marking |
|--------|---------|---------|
| SA12B5 | SO16    | SA12B5  |
| SA16B3 | SO20    | SA16B3  |
| SA16B6 | SSOP20  | SA16B6  |

## PACKAGE MECHANICAL DATA

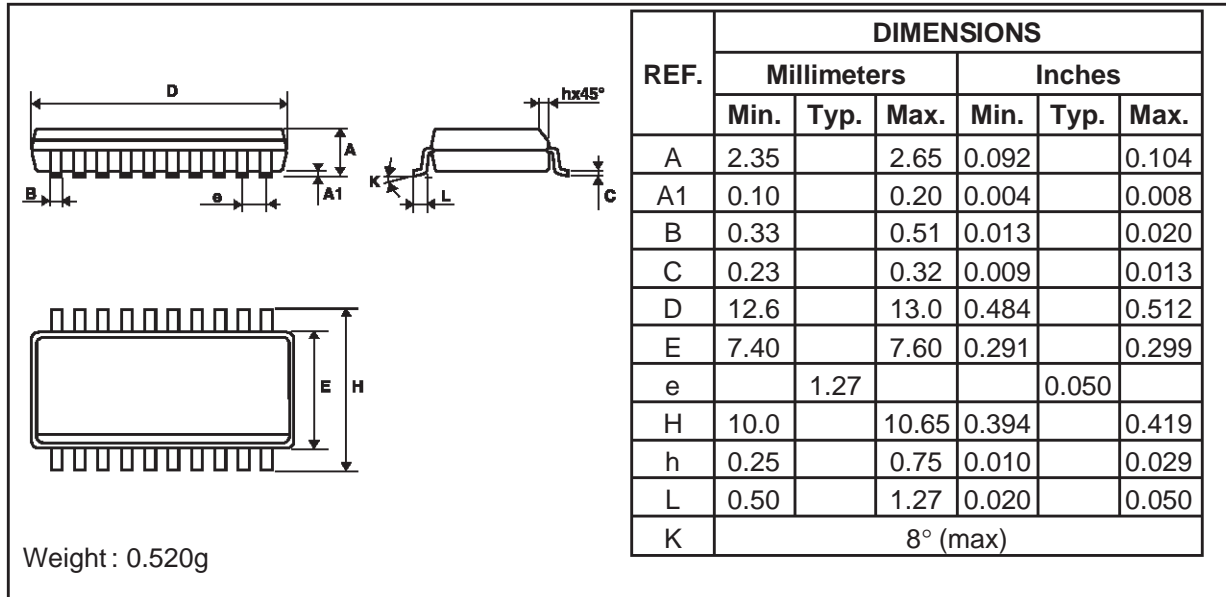
### SO-16

| REF. | DIMENSIONS  |      |      |        |       |       |
|------|-------------|------|------|--------|-------|-------|
|      | Millimeters |      |      | Inches |       |       |
|      | Min.        | Typ. | Max. | Min.   | Typ.  | Max.  |
| A    |             |      | 1.75 |        |       | 0.069 |
| a1   | 0.1         |      | 0.20 | 0.004  |       | 0.008 |
| a2   |             |      | 1.6  |        |       | 0.063 |
| b    | 0.35        |      | 0.46 | 0.014  |       | 0.018 |
| b1   | 0.19        |      | 0.25 | 0.007  |       | 0.010 |
| C    |             | 0.5  |      |        | 0.020 |       |
| c1   | 45°(typ.)   |      |      |        |       |       |
| D    | 9.8         |      | 10   | 0.386  |       | 0.394 |
| E    | 5.8         |      | 6.2  | 0.228  |       | 0.244 |
| e    |             | 1.27 |      |        | 0.050 |       |
| e3   |             | 8.89 |      |        | 0.350 |       |
| F    | 3.8         |      | 4.0  | 0.150  |       | 0.158 |
| G    | 4.6         |      | 5.3  | 0.181  |       | 0.209 |
| L    | 0.5         |      | 1.27 | 0.020  |       | 0.050 |
| M    |             |      | 0.75 |        |       | 0.030 |
| S    | 8°(typ.)    |      |      |        |       |       |

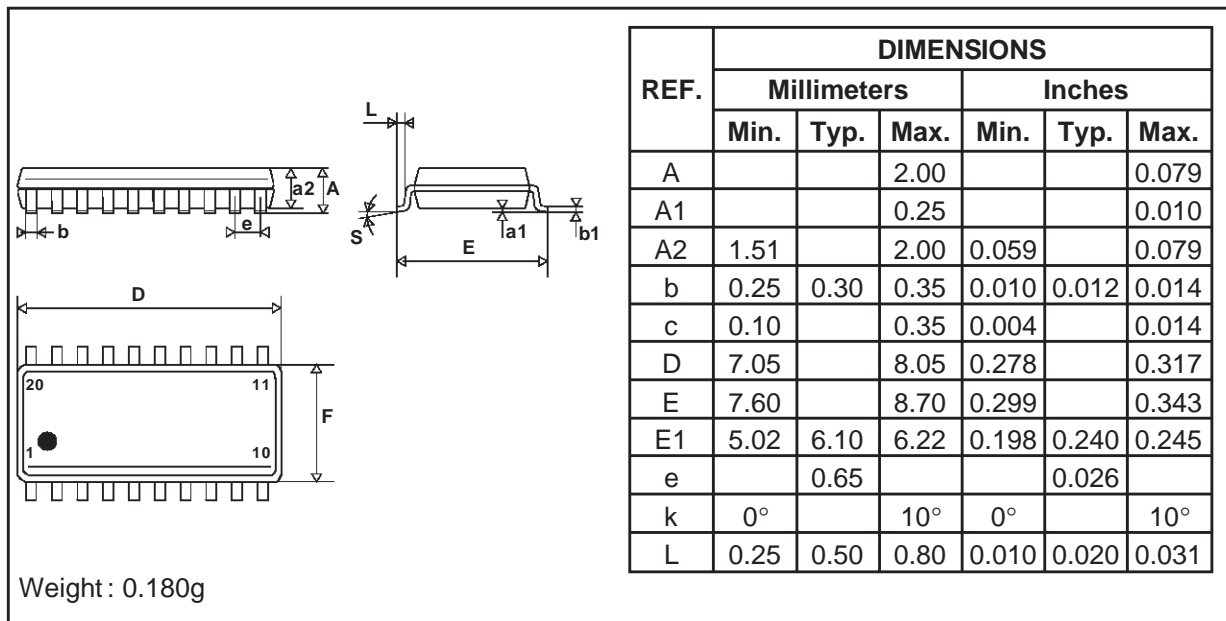


Weight : 0.160g

**PACKAGE MECHANICAL DATA**  
SO-20



SSOP20



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